SOT2098-1

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

1 July 2024 Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	172 HDQFP_EP
Package body material type	P (plastic)
JEDEC package outline code	MO-355 F
Mounting method type	S (surface mount)
Issue date	16-08-2023
Manufacturer package code	98ASA01667D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	15.6	16	16.4	mm
package width	15.6	16	16.4	mm
seated height	-	1.65	1.75	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	172	-	

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

2 Package outline

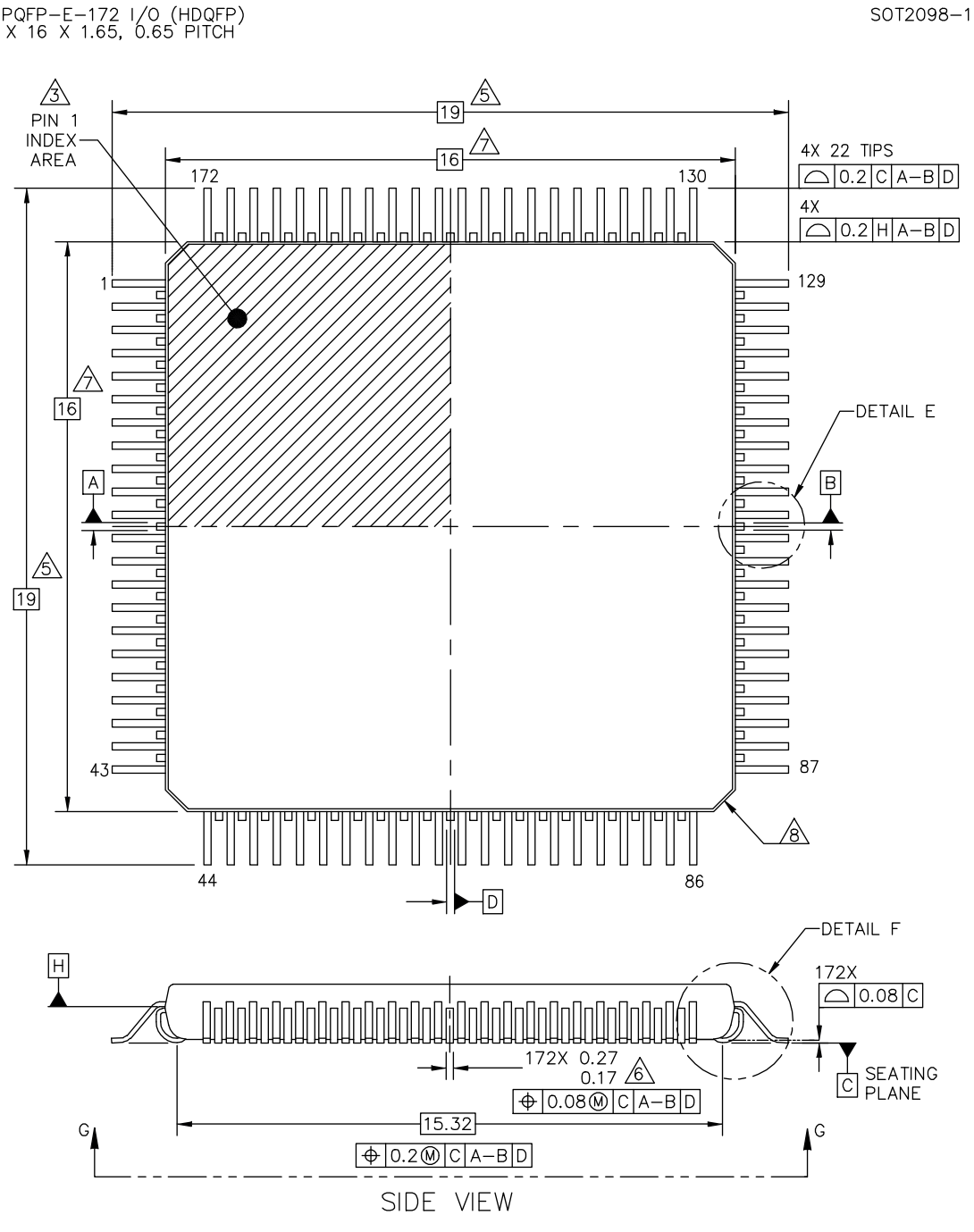


Figure 1. Package outline HQFP172 (SOT2098-1)

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

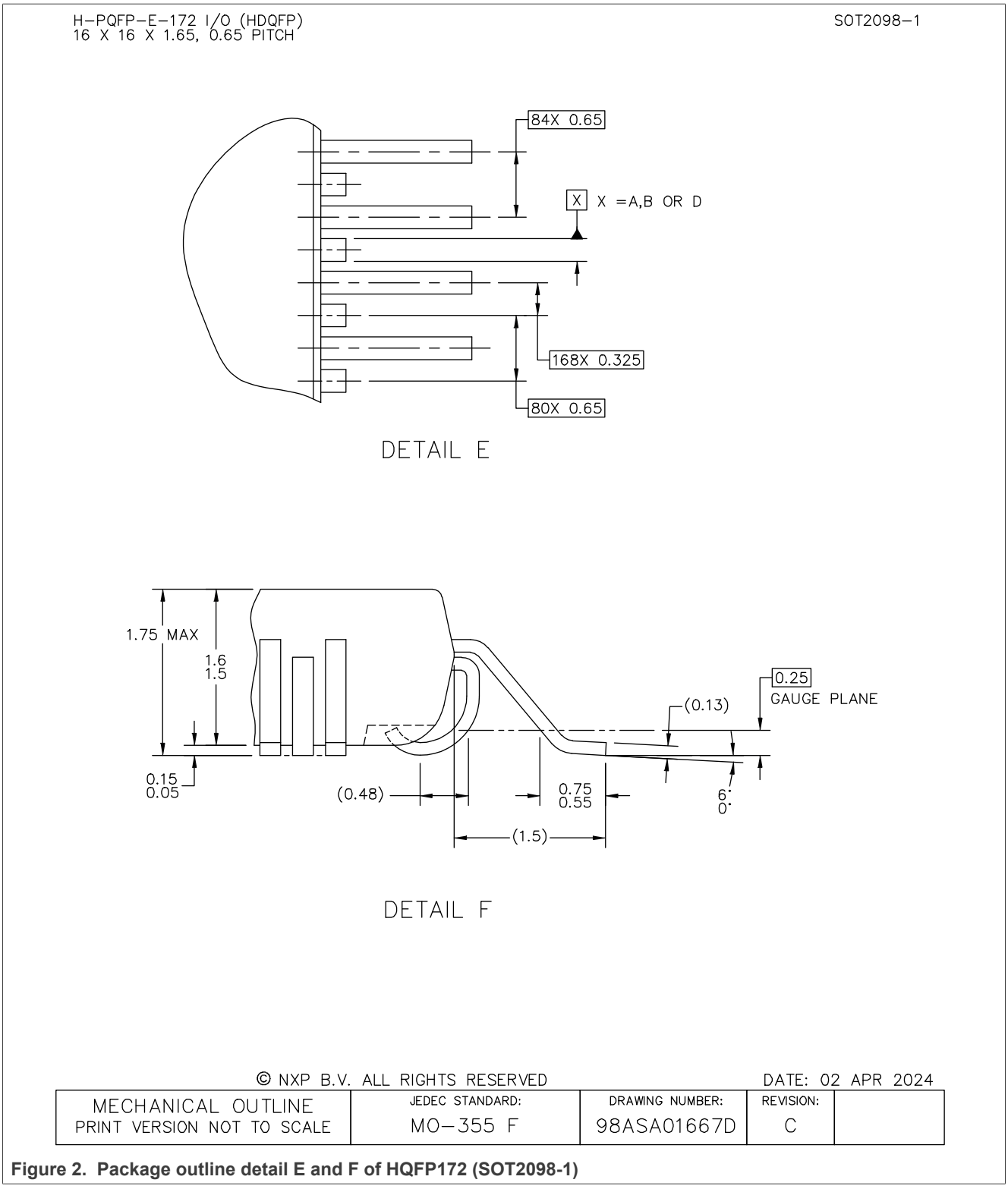


Figure 2. Package outline detail E and F of HQFP172 (SOT2098-1)

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

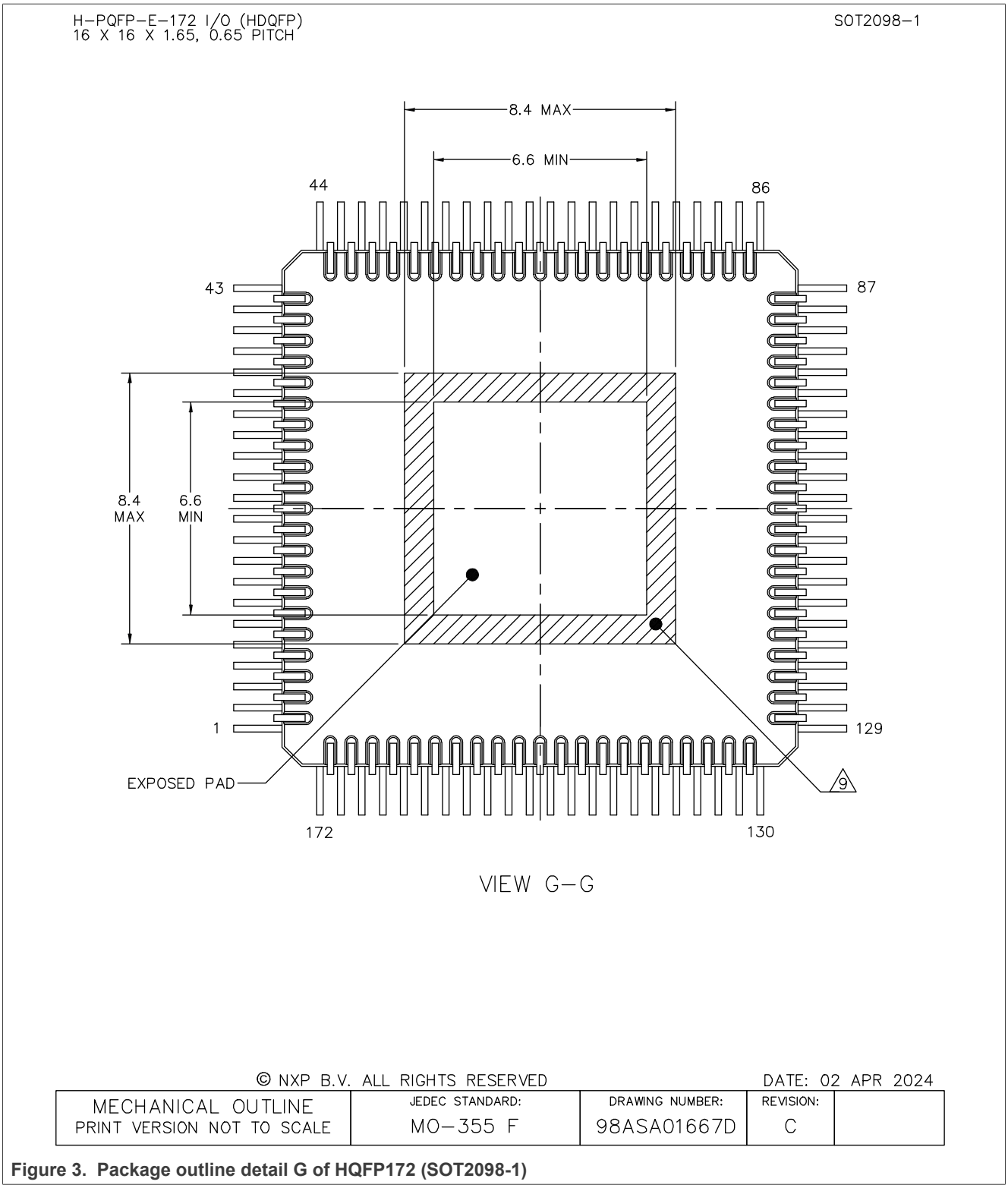


Figure 3. Package outline detail G of HQFP172 (SOT2098-1)

3 Soldering

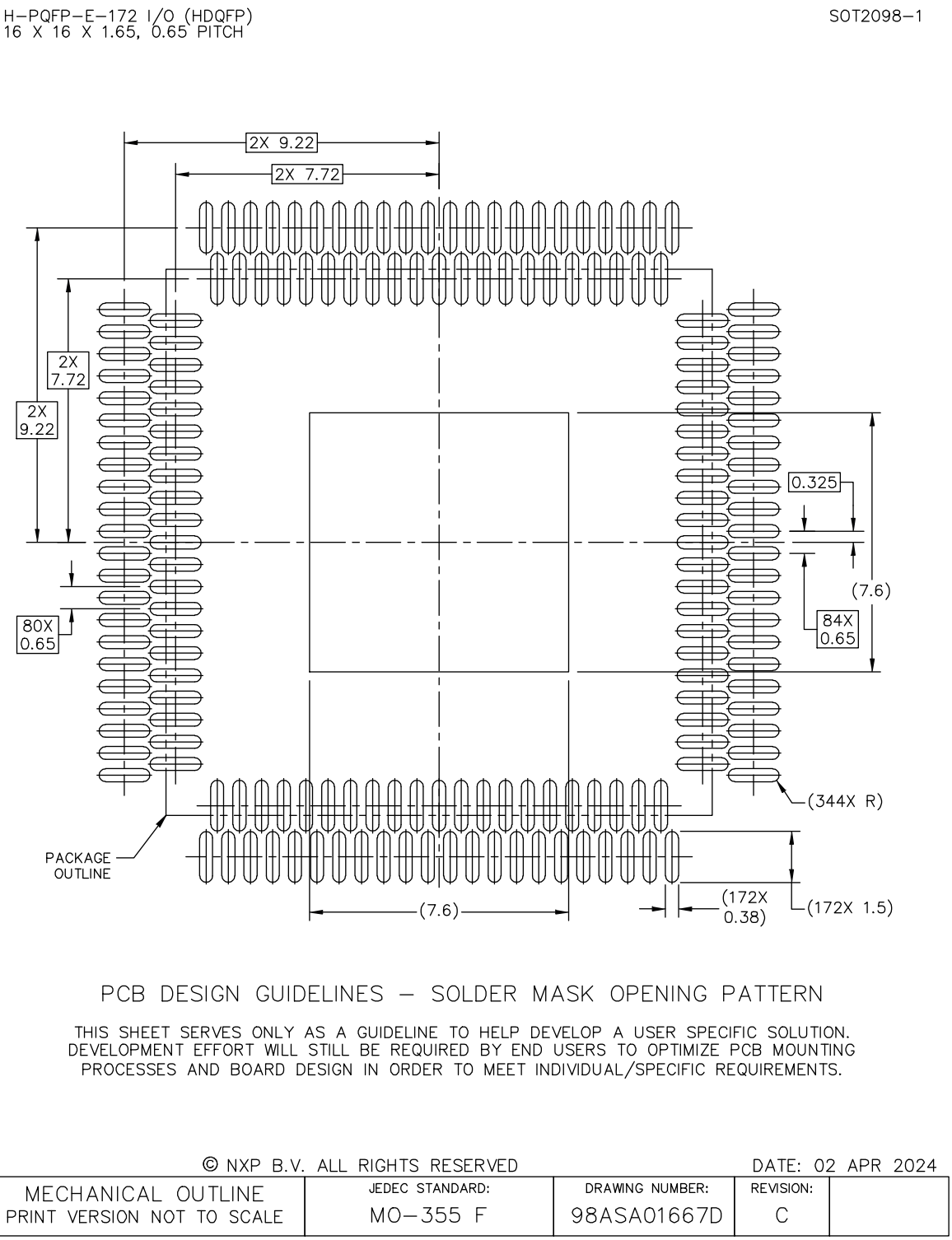
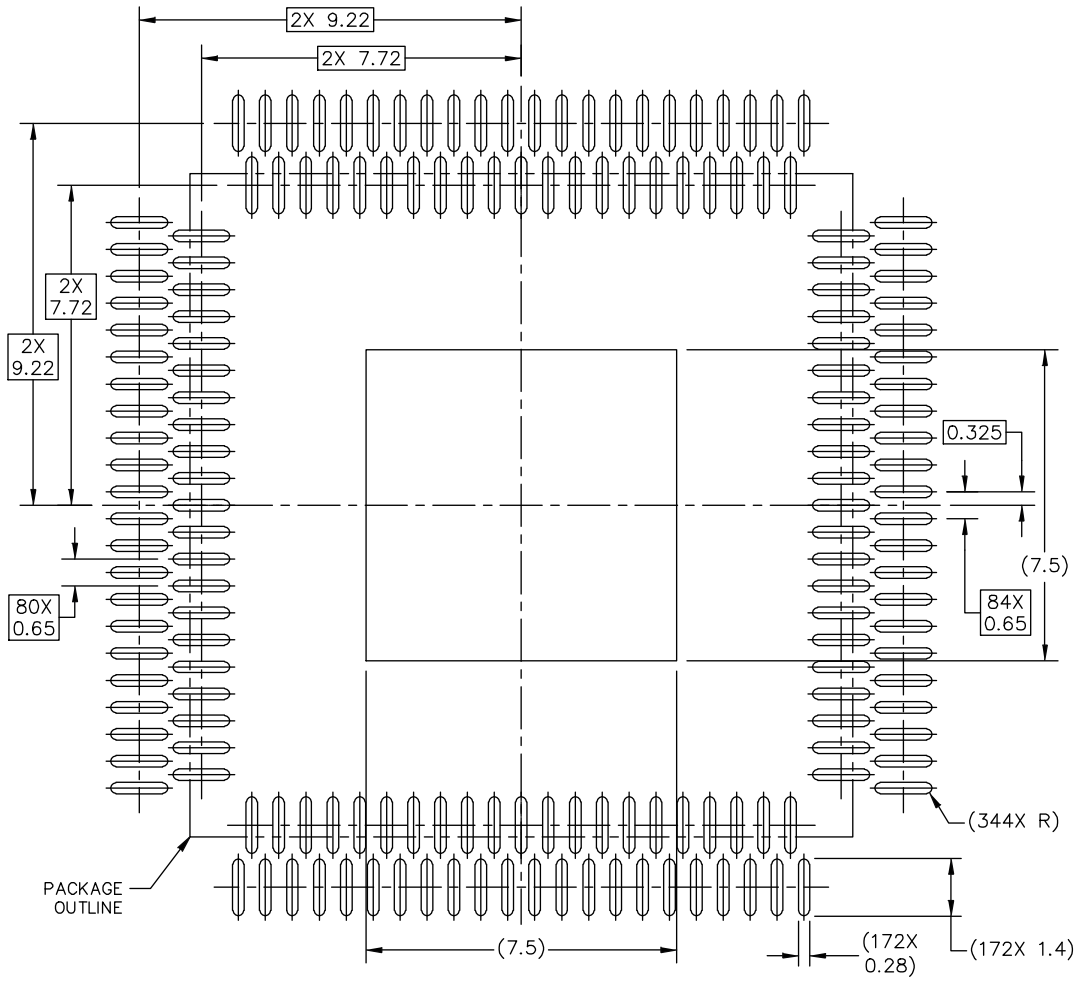


Figure 4. Reflow soldering footprint part1 for HQFP172 (SOT2098-1)

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 02 APR 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	JEDEC STANDARD: MO–355 F	DRAWING NUMBER: 98ASA01667D	REVISION: C	

Figure 5. Reflow soldering footprint part2 for HQFP172 (SOT2098-1)

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

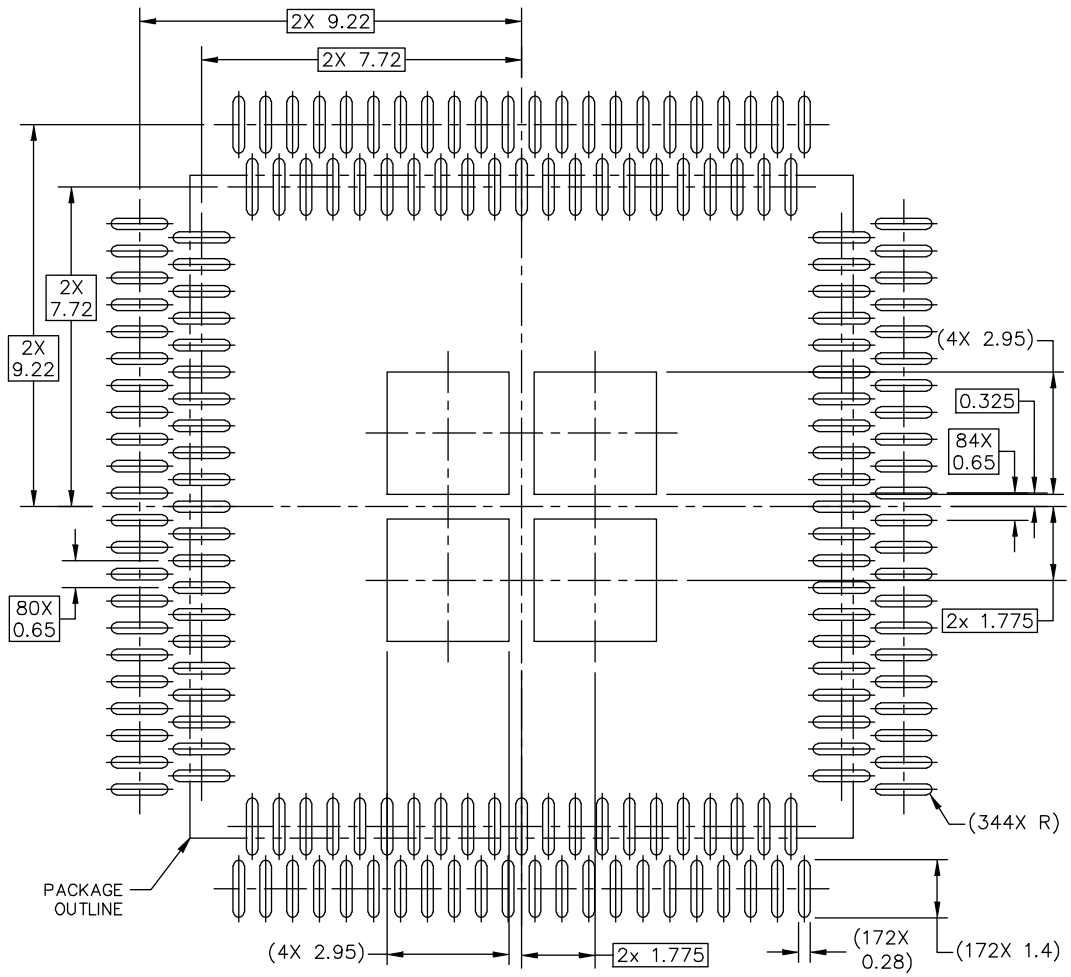


Figure 6. Reflow soldering footprint part3 for HQFP172 (SOT2098-1)

172 HDQFP_EP, thermally enhanced High Density Quad Flat Package_Exposed Pad, 172 leads, 16 x 16 x 1.65, 0.65 mm pitch

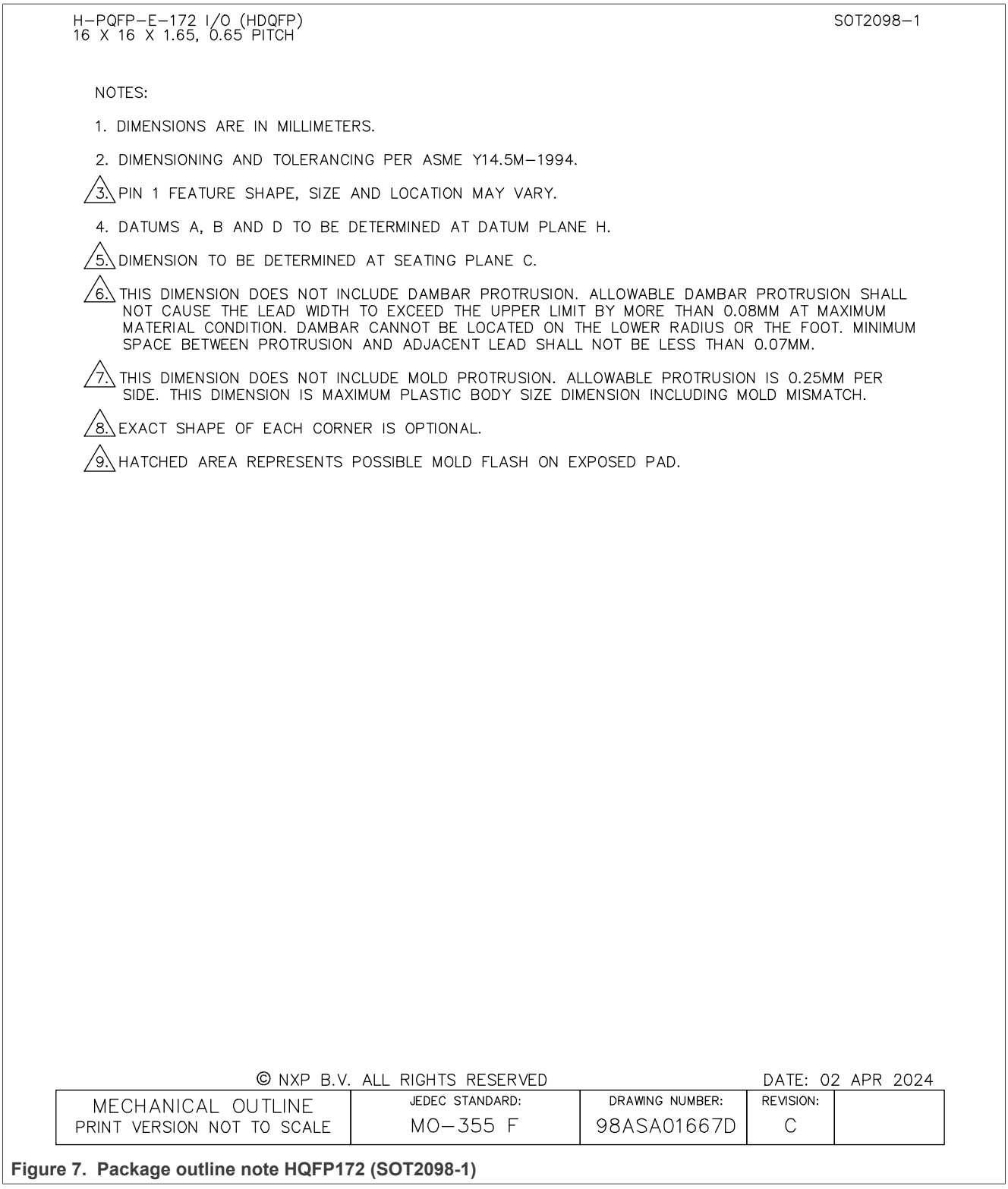


Figure 7. Package outline note HQFP172 (SOT2098-1)

4 Legal information

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For more information, please visit: https://www.nxp.com

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